

SONY

CXP81720A/81724A

CMOS 8-bit Single Chip Microcomputer

Description

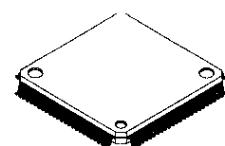
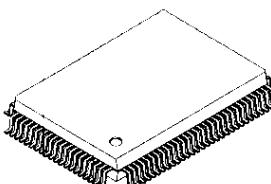
The CXP81720A/81724A is a CMOS 8-bit microcomputer which consists of A/D converter, serial interface, timer/counter, time base timer, vector interruption, high precision timing pattern generation circuit, PWM generator, PWM for tuner, 32kHz timer/event counter, remote control receiving circuit, as well as basic configurations like 8-bit CPU, ROM, RAM and I/O port. They are integrated into a single chip.

Also CXP81720A/81724A provides sleep/stop function which enables to lower power consumption and ultra-low speed instruction mode in 32kHz operation.

Features

- A wide instruction set (213 instructions) which cover various types of data
 - 16-bit arithmetic instruction/multiplication and division instructions/boolean bit operation instruction
- Minimum instruction cycle
 - During operation 250ns/16MHz (Supply voltage 4.5 to 5.5V)
 - During operation 122μs/32kHz
- Incorporated ROM capacity
 - 20K bytes (CXP81720A)
 - 24K bytes (CXP81724A)
- Incorporated RAM capacity
 - 800 bytes
- Peripheral functions
 - A/D converter
 - 8-bit, 12-channel, successive approximation system
(Conversion time 20.0μs/16MHz)
 - Serial interface
 - Incorporated 8-bit and 8-stage FIFO, 1-channel
(1 to 8 bytes auto transfer)
 - 8-bit serial I/O, 1-channel
 - Timer
 - 8-bit timer, 8-bit timer/counter, 19-bit time base timer
 - 32kHz timer/counter
 - High precision timing pattern generator
 - PPG 19 pins 32-stage programmable
 - RTG 5-pins 2-channel
 - PWM/DA gate output
 - 12-bit, 2-channel (Repetitive frequency 62kHz/16MHz)
 - FRC capture unit
 - Incorporated 26-bit and 8-stage FIFO
 - PWM output
 - 14-bit, 1-channel
 - Remote control receiving circuit
 - 8-bit pulse measuring counter, 6-stage FIFO
- Interruption
 - 20 factors, 15 vectors, multi-interruption possible
- Standby mode
 - SLEEP/STOP
- Package
 - 100-pin plastic QFP/LQFP
 - CXP81800 100-pin ceramic QFP/LQFP
- Piggyback/evaluation chip

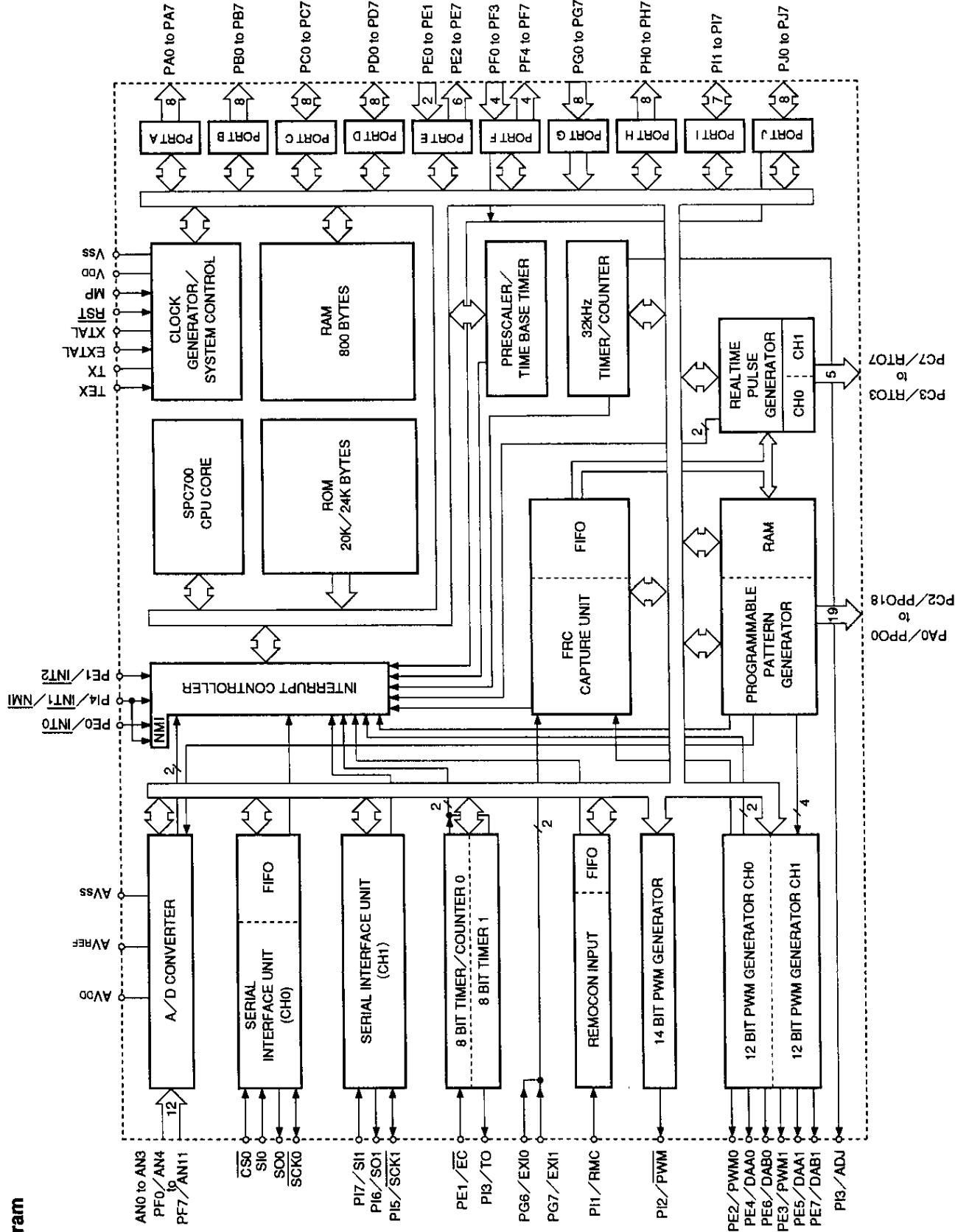
100 pin QFP (Plastic) 100 pin LQFP (Plastic)



Structure

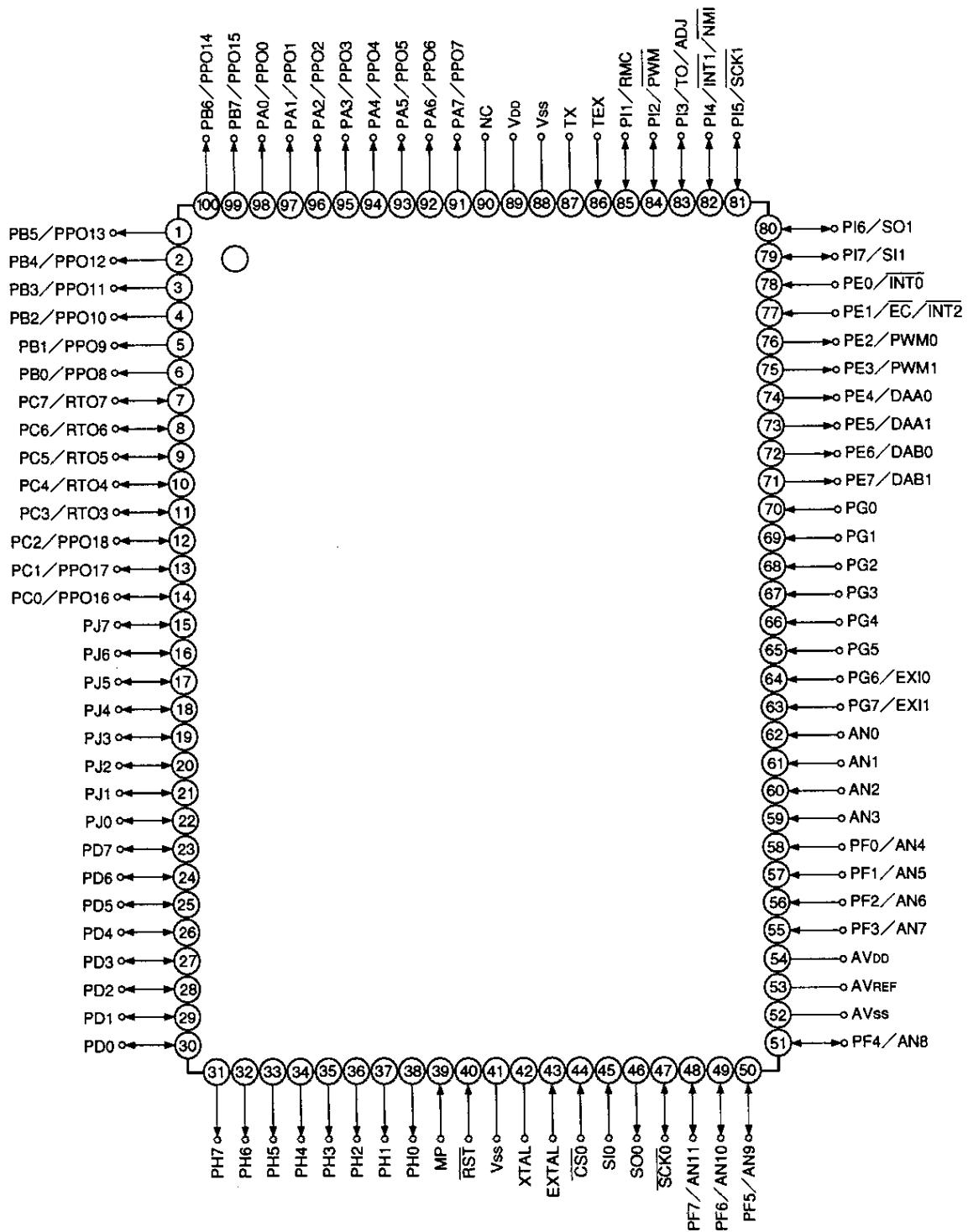
Silicon gate CMOS IC

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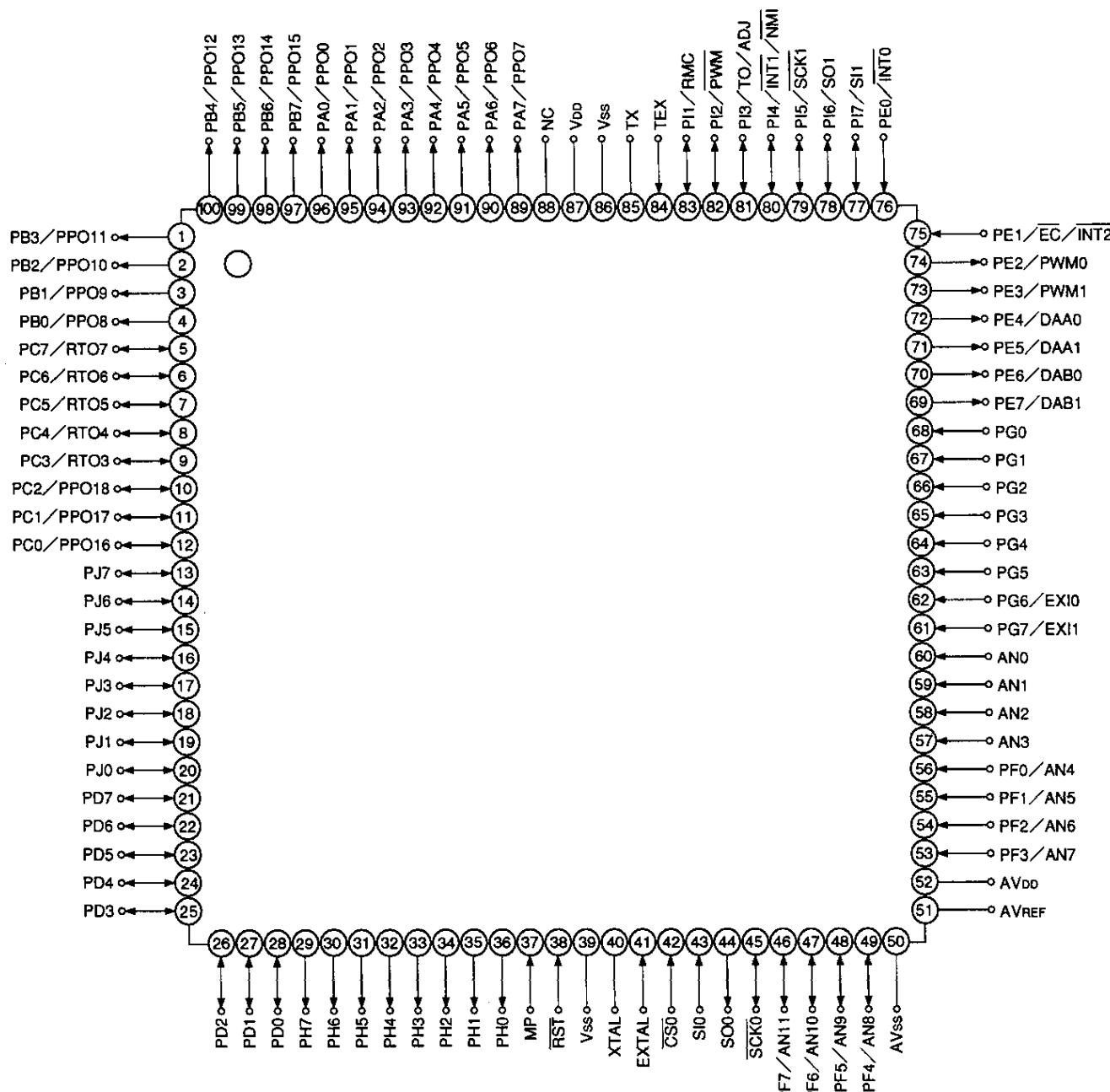
Block Diagram

Pin Configuration 1 (Top View) 100 pin QFP package



Note) 1. NC (Pin 90) is always connected to VDD.
 2. Vss (Pins 41 and 88) are both connected to GND.

Pin Configuration 2 (Top View) 100 pin LQFP package



Note)

1. NC (Pin 88) is always connected to VDD.
2. Vss (Pins 39 and 86) are both connected to GND.

Pin Description

Symbol	I/O	Description	
PA0/PPO0 to PA7/PPO7	Output/ Real time Output	(Port A) 8-bit output port. Data is gated with PPO contents by OR-gate and they are output. (8 pins)	Programmable pattern generator (PPG) output. Functions as high precision real time pulse output port. (19 pins)
PB0/PPO8 to PB7/PPO15	Output/ Real time Output	(Port B) 8-bit output port. Data is gated with PPO contents by OR-gate and they are output. (8 pins)	
PC0/PPO16 to PC2/PPO18	I/O/ Real time Output	(Port C) 8-bit I/O port, enables to specify I/O by bit unit. Data is gated with PPO or RTO contents by OR-gate and they are output. (8 pins)	Real time pulse generator (RTG) output. Functions as high precision real time pulse output port. (5 pins)
PC3/RTO3 to PC7/RTO7	I/O/ Real time Output		
PD0 to PD7	I/O	(Port D) 8-bit I/O port. Enable to specify I/O by 4-bit unit. Enables to drive 12mA sink current. (8 pins)	
PE0/INT0	Input/input	(Port E) 8-bit port. Lower 2 bits are input pins and upper 6 bits are output pins. (8 pins)	Input pin to request external interruption. Active when falling edge.
PE1/EC/INT2	Input/input/input		External event input pin for timer/counter. Input pin to request external interruption. Active when falling edge.
PE2/PWM0	Output/output		PWM output pins. (2 pins)
PE3/PWM1	Output/output		
PE4/DAA0	Output/output		
PE5/DAA1	Output/output		
PE6/DAB0	Output/output		DA gate pulse output pins. (4 pins)
PE7/DAB1	Output/output		
AN0 to AN3	Input	Analog input pins to A/D converter. (12 pins)	
PF0/AN4 to PF3/AN7	Input/input	(Port F) Lower 4 bits are input port and upper 4 bits are output port. Lower 4 bits also serve as standby release input pin. (8 pins)	
PF4/AN8 to PF7/AN11	Output/input		
SCK0	I/O	Serial clock (CH0) I/O pin.	
SO0	Ouput	Serial data (CH0) output pin.	
SI0	Input	Serial data (CH0) input pin.	
CS0	Input	Serial chip select (CH0) input pin.	

Symbol	I/O	Description	
PG0 to PG5	Input	(Port G) 8-bit input port. (8 pins)	External input pin to FRC capture unit.
PG6/EXI0	Input/input		
PG7/EXI1	Input/input		
PH0 to PH7	Output	(Port H) N-ch open drain output of middle tension proof (12V) and high current (12mA). (8 pins)	
PI1/RMC	I/O/input	(Port I) 7-bit I/O port. I/O port can be specified by the bit unit. (7 pins)	Remote control receiving circuit input pin.
PI2/PWM	I/O/output		14-bit PWM output pin.
PI3/TO/ADJ	I/O/output/output		Timer/counter, 32kHz oscillation adjustment output pin.
PI4/INT1/ NMI	I/O/input/input		Input pin to request external interruption and non maskable interruption. Active when falling edge.
PI5/SCK1	I/O/I/O		Serial clock (CH1) I/O pin.
PI6/SO1	I/O/output		Serial data (CH1) output pin.
PI7/SI1	I/O/input		Serial data (CH1) input pin.
PJ0 to PJ7	I/O	(Port J) 8-bit I/O port. Function as standby release input can be specified by the bit unit. I/O can be specified by the bit unit.	
EXTAL	Input	Connecting pin of crystal oscillator for system clock. When supplying the external clock, input the external clock to EXTAL pin and input opposite phase clock to XTAL pin.	
XTAL	Output		
TEX	Input	Connecting pin of crystal oscillator for 32kHz timer clock. When used as event counter, input to TEX pin and leave TX pin open. (Feedback resistor is not removed.)	
TX	Output		
RST	Input	System reset pin of active "Low" level.	
MP	Input	Microprocessor mode input pin. Always connect to GND.	
AVDD		Positive power supply pin of A/D converter.	
AVREF	Input	Reference voltage input pin of A/D converter.	
AVss		GND pin of A/D converter.	
VDD		Positive power supply pin.	
Vss		GND pin. Connect both Vss pins to GND.	

Input/Output Circuit Formats for Pins

Pin	Circuit format	When reset
PA0/PPO0 to PA7/PPO7 PB0/PPO8 to PB7/PPO15 16 pins	<p>Port A</p> <p>Port B</p> <p>PPO data</p> <p>Port A or Port B</p> <p>Data bus</p> <p>RD</p> <p>Output becomes active from high impedance by data writing to port register.</p>	Hi-Z
PC0/PPO16 to PC2/PPO18 PC3/RTO3 to PC7/RTO7 8 pins	<p>Port C</p> <p>PPO, RTO data</p> <p>Port C data</p> <p>Port C direction</p> <p>Data bus</p> <p>RD (Port C)</p> <p>(Every bit)</p> <p>IP</p> <p>Input protection circuit</p>	Hi-Z
PD0 to PD7 8 pins	<p>Port D</p> <p>Port D data</p> <p>Port D direction</p> <p>Data bus</p> <p>RD (Port D)</p> <p>(Every 4 bits) (PD0 to 3) (PD4 to 7)</p> <p>IP</p> <p>High current 12mA</p>	Hi-Z

Pin	Circuit format	When reset
PE0/INT0 PE1/EC/INT2 2 pins	<p>Port E</p>	Hi-Z
PE2/PWM0 PE3/PWM1 PE4/DAA0 PE5/DAA1 4 pins	<p>Port E</p>	Hi-Z
PE6/DAB0 PE7/DAB1 2 pins	<p>Port E</p>	H level
AN0 to AN3 4 pins		Hi-Z
PF0/AN4 to PF3/AN7 4 pins	<p>Port F</p>	Hi-Z

Pin	Circuit format	When reset
PF4/AN8 to PF7/AN11 4 pins	<p>Port F</p>	Hi-Z
PG0 to PG5 6 pins	<p>Port G</p>	Hi-Z
PG6/EXI0 PG7/EXI1 2 pins	<p>Port G</p>	Hi-Z
PH0 to PH7 8 pins	<p>Port H</p>	Hi-Z
PI2/PWM PI3/TO/ADJ 2 pins	<p>Port I</p>	Hi-Z

Pin	Circuit format	When reset
PI1/RMC PI4/INT1/NMI PI7/SI1 3 pins	<p>Port I</p> <p>Port I data</p> <p>Port I direction</p> <p>Data bus</p> <p>RD (Port I)</p> <p>Schmitt input</p> <p>PI1...To remote control circuit PI4...To interruption circuit PI7...To serial CH1</p>	Hi-Z
PI5/SCK1 PI6/SO1 2 pins	<p>Port I</p> <p>Port I function select</p> <p>From serial CH1</p> <p>MPX</p> <p>MPX</p> <p>Port I data</p> <p>Port I direction</p> <p>Data bus</p> <p>RD (Port I)</p> <p>To serial CH1</p> <p>Note) PI5 is schmitt input PI6 is inverter input</p>	Hi-Z
PJ0 to PJ7 8 pins	<p>Port J</p> <p>Port J data</p> <p>Port J direction</p> <p>Data bus</p> <p>RD (Port J)</p> <p>Edge detection</p> <p>Standby release</p> <p>Schmitt input</p>	Hi-Z
CS0 SIO 2 pins	<p>Schmitt input</p> <p>To SIO</p>	Hi-Z
SO0 1 pin	<p>SO0 from SIO</p> <p>SO0 output enable</p>	Hi-Z

Pin	Circuit format	When reset
SCK0 1 pin	<p>Internal serial clock from SIO</p> <p>SCK0 output enable</p> <p>External serial clock to SIO</p> <p>Schmitt input</p>	Hi-Z
EXTAL XTAL 2 pins	<p>EXTAL</p> <p>XTAL</p> <ul style="list-style-type: none"> Shows the circuit composition during oscillation. Feedback resistor is removed during stop. XTAL becomes "H" level. 	Oscillation
TEX TX 2 pins	<p>TEX</p> <p>TX</p> <p>32kHz timer counter</p> <ul style="list-style-type: none"> Shows the circuit composition during oscillation. Feedback resistor is removed during 32kHz oscillation circuit stop by software. At this time TEX pin outputs "L" level and TX pin outputs "H" level. 	Oscillation
RST 1 pin	<p>Mask option</p> <p>Pull-up resistor</p> <p>Schmitt input</p>	L level
MP 1 pin	<p>IP</p> <p>CPU mode</p>	Hi-Z

Absolute Maximum Ratings

(Vss=0V)

Item	Symbol	Rating	Unit	Remarks
Supply voltage	VDD	-0.3 to +7.0	V	
	AVDD	AVss to +7.0*1	V	
	AVss	-0.3 to +0.3	V	
Input voltage	VIN	-0.3 to +7.0*2	V	
Output voltage	VOUT	-0.3 to +7.0*2	V	
Medium withstand output voltage	VOUTP	-0.3 to +15.0	V	PH pin
High level output current	IOH	-5	mA	
High level total output current	Σ IOH	-50	mA	Total of output pins
Low level output current	IOL	15	mA	Other than high current output pins: per pin
	IOLC	20	mA	High current port pin*3: per pin
Low level total output current	Σ IOL	130	mA	Total of output pins
Operating temperature	Topr	-20 to +75	°C	
Storage temperature	Tstg	-55 to +150	°C	
Allowable power dissipation	PD	600	mW	QFP package type
		380		LQFP package type

*1) AVDD and VDD should be set to a same voltage.

*2) VIN and VOUT should not exceed VDD+0.3V.

*3) The high current operation transistors are the N-CH transistors of the PD and PH ports.

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should better take place under the recommended operating conditions. Exceeding those conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions

(Vss=0V)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	VDD	4.5	5.5	V	Guaranteed range during high speed mode (1/2 dividing clock) operation
		3.5	5.5		Guaranteed range during low speed mode (1/16 dividing clock) operation
		2.7	5.5		Guaranteed operation range by TEX clock
		2.5	5.5		Guaranteed data hold operation range during STOP
Analog power supply	AVDD	3.0	5.5	V	*1
High level input voltage	VIH	0.7VDD	VDD	V	*2
	VIHS	0.8VDD	VDD	V	CMOS schmitt input*3
	VIHTS	2.2	VDD	V	TTL schmitt input*4
	VIHES	VDD-0.4	VDD+0.3	V	EXTAL pin*5 TEX pin*6
Low level input voltage	VIL	0	0.3VDD	V	*2
	VILS	0	0.2VDD	V	CMOS schmitt input*3
	VILTS	0	0.8	V	TTL schmitt input*4
	VILEX	-0.3	0.4	V	EXTAL pin*5 TEX pin*6
Operating temperature	Topr	-20	+75	°C	

*1) AVDD and VDD should be set to a same voltage.

*2) Normal input port (each pin of PC, PD, PE0, PE1, PF0 to PF3, PG, PI and PJ), MP pin.

*3) Each pin of CS0, SI0, SCK0, RST, PE0/INT0, PE1/EC/INT2, PG (For PG4 and PG5, when CMOS schmitt input is selected with mask option), PI1/RMC, PI4/INT1/NMI, PI5/SCK1 and PI7/SI1.

*4) Each pin of PG4 and PG5 (When TTL schmitt input is selected with mask option)

*5) It specifies only when the external clock is input.

*6) It specifies only when the event count clock is input.

Electrical Characteristics**DC Characteristics (V_{DD}=4.5 to 5.5V)**(Ta=-20 to +75°C, V_{SS}=0V)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA to PD, PE2 to PE7, PF4 to PF7, PH (Vol only) PI1 to PI7 PJ, SO0, SCK0	V _{DD} =4.5V, I _{OH} =-0.5mA	4.0			V
			V _{DD} =4.5V, I _{OH} =-1.2mA	3.5			V
Low level output voltage	V _{OL}	PD, PH	V _{DD} =4.5V, I _{OL} =1.8mA			0.4	V
			V _{DD} =4.5V, I _{OL} =3.6mA			0.6	V
Input current	I _{IE}	EXTAL	V _{DD} =5.5V, V _{IH} =5.5V	0.5		40	μA
	I _{IL}		V _{DD} =5.5V, V _{IL} =0.4V	-0.5		-40	μA
	I _{HT}	TEX	V _{DD} =5.5V, V _{IH} =5.5V	0.1		10	μA
	I _{LT}		V _{DD} =5.5V, V _{IL} =0.4V	-0.1		-10	μA
	I _{LR}	RST*1		-1.5		-400	μA
I/O leakage current	I _{Iz}	PA to PG, PI, PJ, MP AN0 to AN3, CS0, SI0, SO0 SCK0, RST*1	V _{DD} =5.5V, V _I =0, 5.5V			±10	μA
Open drain output leakage current (N-CH Tr OFF in state)	I _{LOH}	PH	V _{DD} =5.5V V _{OH} =12V			50	μA
Supply current*2	IDD1	V _{DD}	16MHz crystal oscillation (C ₁ =C ₂ =15pF) V _{DD} =5V±0.5V*3		22	45	mA
	IDDS1		SLEEP mode V _{DD} =5V±0.5V		1.1	8	mA
	IDD2		32kHz crystal oscillation (C ₁ =C ₂ =47pF) V _{DD} =3V±0.3V		35	100	μA
	IDDS2		SLEEP mode V _{DD} =3V±0.3V		9	30	μA
	IDDS3		STOP mode (EXTAL and TEX pins oscillation stop) V _{DD} =5V±0.5V			10	μA
Input capacity	C _{IN}	Other than V _{DD} , V _{SS} , AV _{DD} , and AV _{SS}	Clock 1MHz 0V other than the measured pins		10	20	pF

*1) RST pin specifies the input current when the pull-up resistor is selected, and specifies leakage current when non-resistor is selected.

*2) When entire output pins are open.

*3) When setting upper 2 bits (CPU clock selection) of clock control register CLC (address: 00FEH) to "00" and operating in high speed mode (1/2 dividing clock).

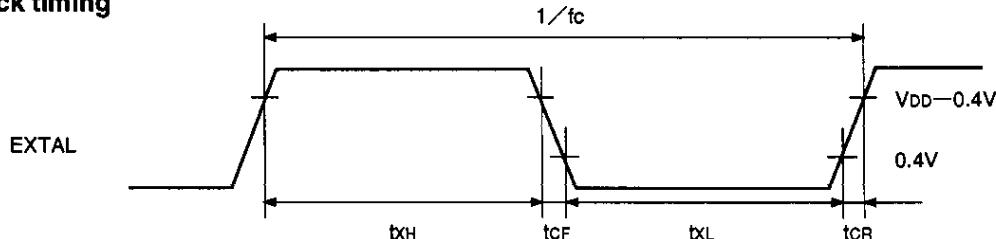
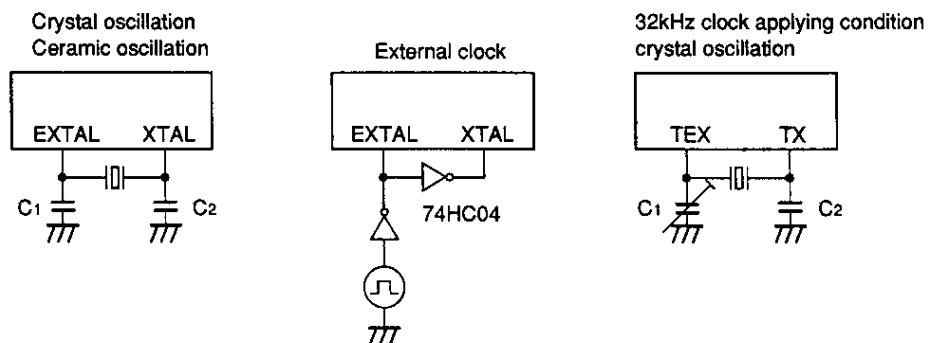
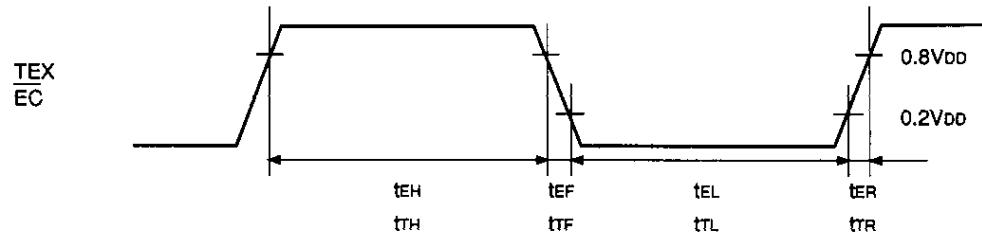
AC Characteristics**(1) Clock timing**

(Ta=-20 to +75°C, VDD=4.5 to 5.5V, Vss=0V)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	1	16	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 (External clock drive)	28		ns
System clock input rise and fall times	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 (External clock drive)		200	ns
Event count clock input pulse width	t _{EH} , t _{EL}	EC	Fig. 3	t _{sys} x 4*		ns
Event count clock input rise and fall times	t _{ER} , t _{EF}	EC	Fig. 3		20	ns
System clock frequency	fc	TEX TX	Fig. 2 VDD=2.7 to 5.5V (32kHz clock applied condition)	32.768		kHz
Event count clock input pulse width	t _{TL} , t _{TH}	TEX	Fig. 3	10		μs
Event count clock input rise and fall times	t _{TR} , t _{TF}	TEX	Fig. 3		20	ms

* t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH) upper 2 bits (CPU clock selection).

t_{sys} [ns]=2000/fc (Upper 2-bit="00"), 4000/fc (Upper 2-bit="01"), 16000/fc (Upper 2-bit="11")

Fig. 1. Clock timing**Fig. 2. Clock applied condition****Fig. 3. Event count clock timing**

(2) Serial transfer (CH0)

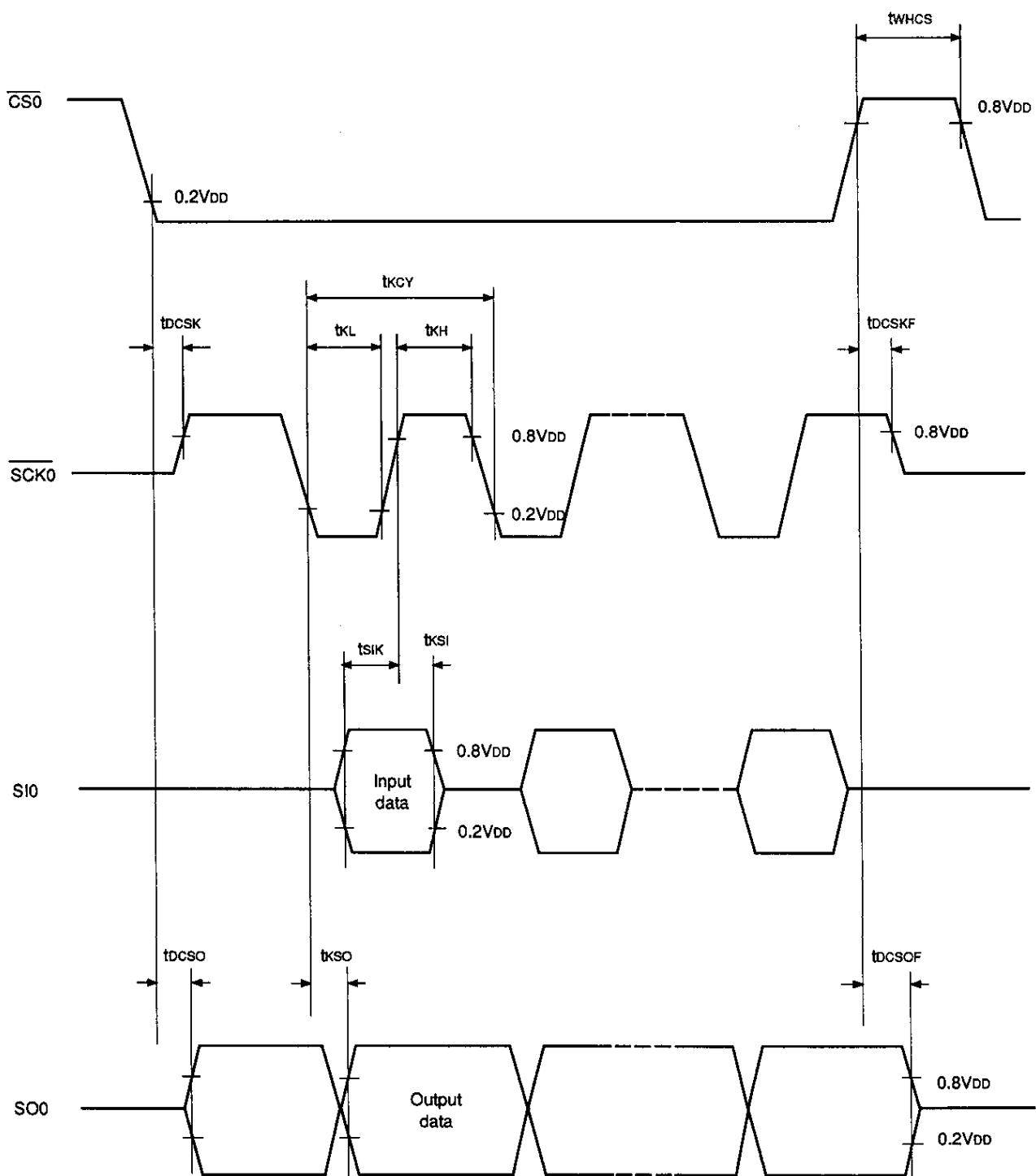
(Ta=-20 to +75°C, V_{DD}=4.5 to 5.5V, V_{SS}=0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CS0 ↓ → SCK0 delay time	t _{DCSK}	SCK0	Chip select transfer mode (SCK0=output mode)		t _{sys} +200	ns
CS0 ↑ → SCK0 floating delay time	t _{DCSKF}	SCK0	Chip select transfer mode (SCK0=output mode)		t _{sys} +200	ns
CS0 ↓ → SO0 delay time	t _{DCSO}	SO0	Chip select transfer mode		t _{sys} +200	ns
CS0 ↑ → SO0 floating delay time	t _{DCSOF}	SO0	Chip select transfer mode		t _{sys} +200	ns
CS0 high level width	t _{WHCS}	CS0	Chip select transfer mode	t _{sys} +200		ns
SCK0 cycle time	t _{KCY}	SCK0	Input mode	2t _{sys} +200		ns
			Output mode	16000/fc		ns
SCK0 high and low level widths	t _{KH} t _{KL}	SCK0	Input mode	t _{sys} +100		ns
			Output mode	8000/fc-50		ns
SI0 input setup time (against SCK0 ↑)	t _{SIK}	SI0	SCK0 input mode	100		ns
			SCK0 output mode	200		ns
SI0 input hold time (against SCK0 ↑)	t _{KSI}	SI0	SCK0 input mode	t _{sys} +200		ns
			SCK0 output mode	100		ns
SCK0 ↓ → SO0 delay time	t _{KSO}	SO0	SCK0 input mode		t _{sys} +200	ns
			SCK0 output mode		100	ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH)
upper 2 bits (CPU clock selection).

t_{sys} [ns]=2000/fc (Upper 2-bit="00"), 4000/fc (Upper 2-bit="01"), 16000/fc (Upper 2-bit="11")

Note 2) The load of SCK0 output mode and SO0 output delay time is 50pF+1TTL.

Fig. 4. Serial transfer CH0 timing

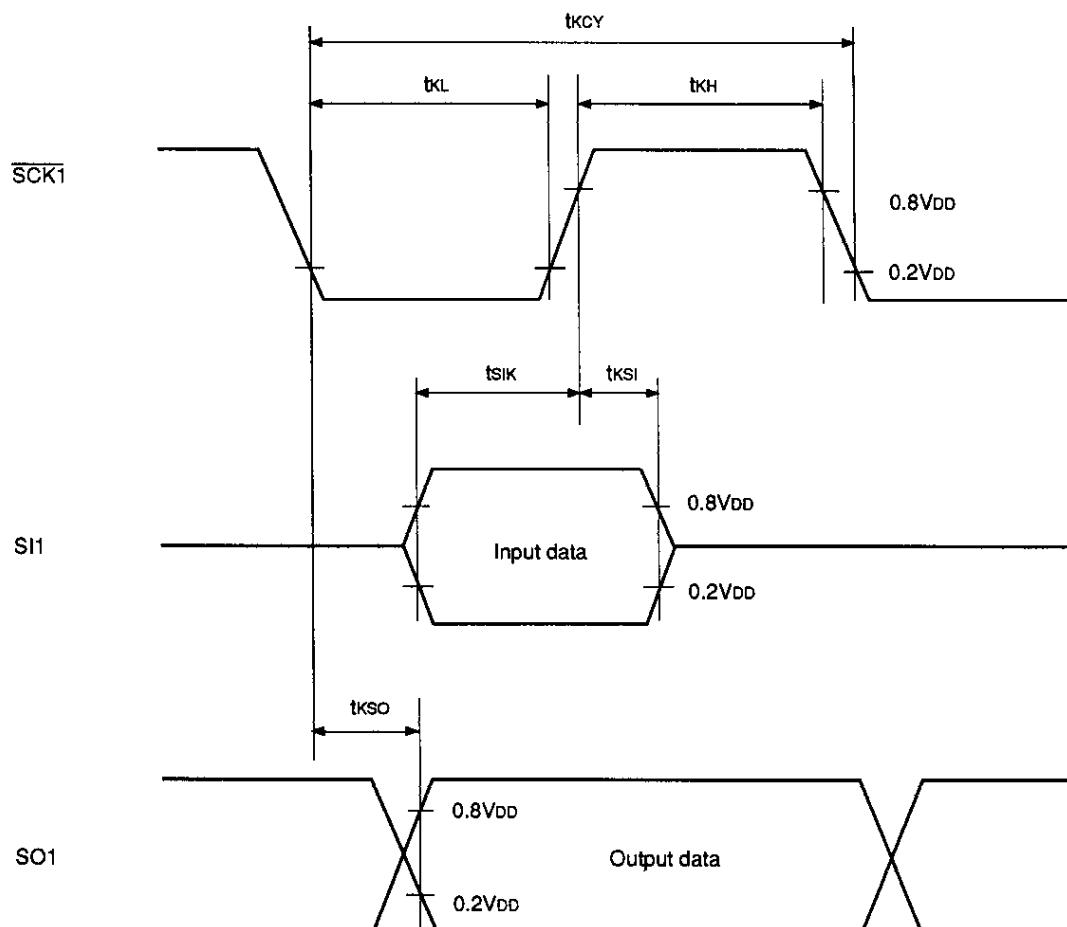
Serial transfer (CH1)

(Ta=-20 to +75°C, VDD=4.5 to 5.5V, Vss=0V)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
<u>SCK1</u> cycle time	tkCY	<u>SCK1</u>	Input mode	1000		ns
			Output mode	16000/fc		ns
<u>SCK1</u> high and low level widths	tKH tKL	<u>SCK1</u>	Input mode	400		ns
			Output mode	8000/fc-50		ns
SI1 input setup time (against SCK1 ↑)	tsIK	SI1	SCK1 input mode	100		ns
			SCK1 output mode	200		ns
SI1 input hold time (against SCK1 ↑)	tksi	SI1	SCK1 input mode	200		ns
			SCK1 output mode	100		ns
<u>SCK1</u> ↓ → SO1 delay time	tkso	SO1	SCK1 input mode		200	ns
			SCK1 output mode		100	ns

Note) The load of SCK1 output mode and SO1 output delay time is 50pF+1TTL.

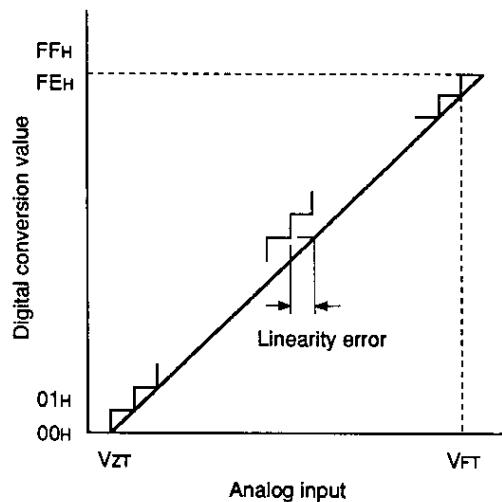
Fig. 5. Serial transfer CH1 timing



(3) A/D converter characteristics (Ta=-20 to +75°C, VDD=AVDD=4.5 to 5.5V, AVREF=4.0 to AVDD, Vss=AVss=0V)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error			Ta=25°C VDD=AVDD=AVREF=5.0V			±1	LSB
Absolute error			VSS=AVSS=0V			±2	LSB
Conversion time	t _{CONV}			160/f _{ADC} *			μs
Sampling time	t _{SAMP}			12/f _{ADC} *			μs
Reference input voltage	V _{REF}	AV _{REF}	VDD=AVDD=4.5 to 5.5V	AVDD-0.5		AVDD	V
Analog input voltage	V _{IAN}	AN0 to AN11		0			V
AV _{REF} current	I _{REF}	AV _{REF}	Operating mode		0.6	1.0	mA
	I _{REFS}		SLEEP mode STOP mode 32kHz operating mode			10	μA

Fig. 6. Definitions of A/D converter terms



* The value of f_{ADC} is as follows by selecting ADC operation clock (MSC: Address 01FFH bit 0).

When PS2 is selected, f_{ADC}=fc/2

When PS1 is selected, f_{ADC}=fc

(4) Interruption, reset input

(Ta=-20 to +75°C, VDD=4.5 to 5.5V, Vss=0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption high and low level widths	t_{IH} t_{IL}	INT0 INT1 INT2 NMI PJ0 to PJ7		1		μs
Reset input low level width	t_{RSL}	RST		32/fc		μs

Fig. 7. Interruption input timing

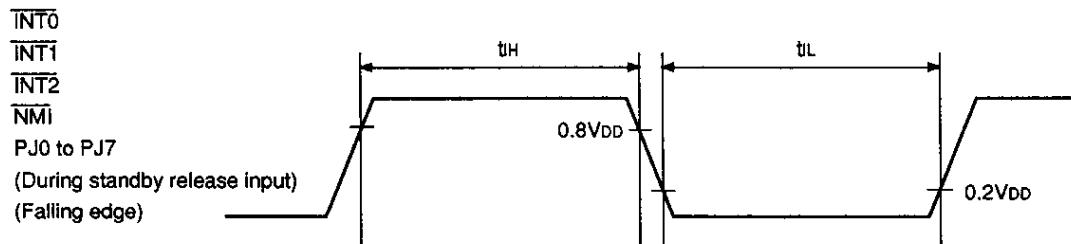
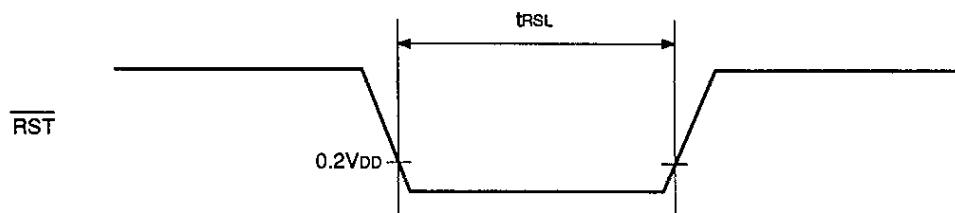


Fig. 8. Reset input timing



(5) Others

(Ta=-20 to +75°C, VDD=4.5 to 5.5V, Vss=0V)

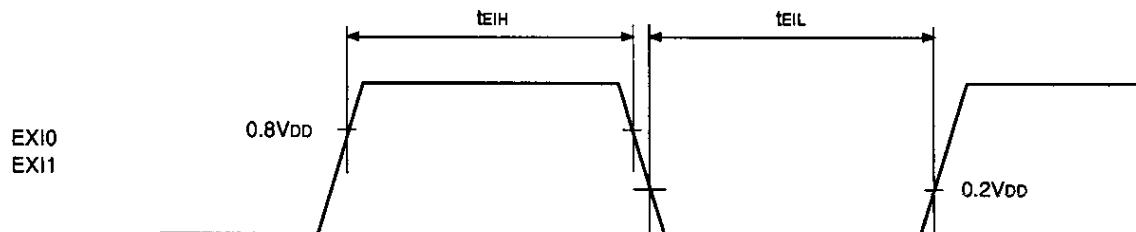
Item	Symbol	Pin	Condition	Min.	Max.	Unit
EXI input high and low level width	t_{EIH} t_{EIL}	EXI0 EXI1	$t_{sys}=2000/fc$	$t_{sys}+200$		ns

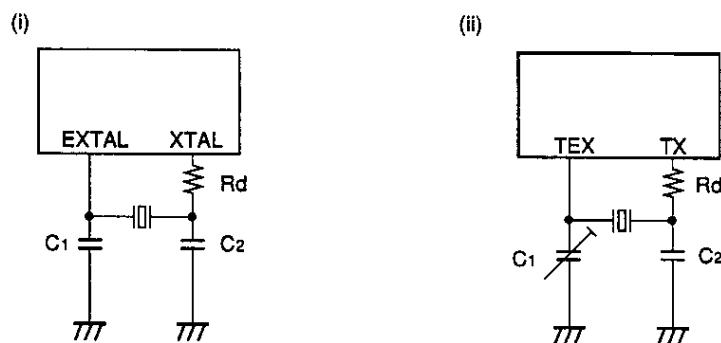
Note) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH)
upper 2 bits (CPU clock selection).

t_{sys} [ns]=2000/fc (Upper 2-bit="00"), 4000/fc (Upper 2-bit="01"), 16000/fc (Upper 2-bit="11")

t_{FRC} [ns]=1000/fc

Fig. 9. Other timings



Supplement**Fig. 10. Recommended oscillation circuit**

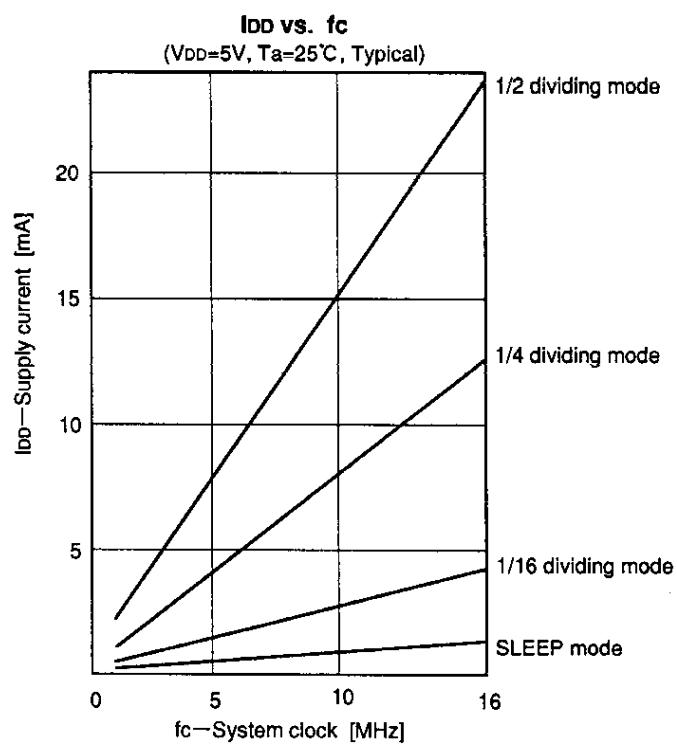
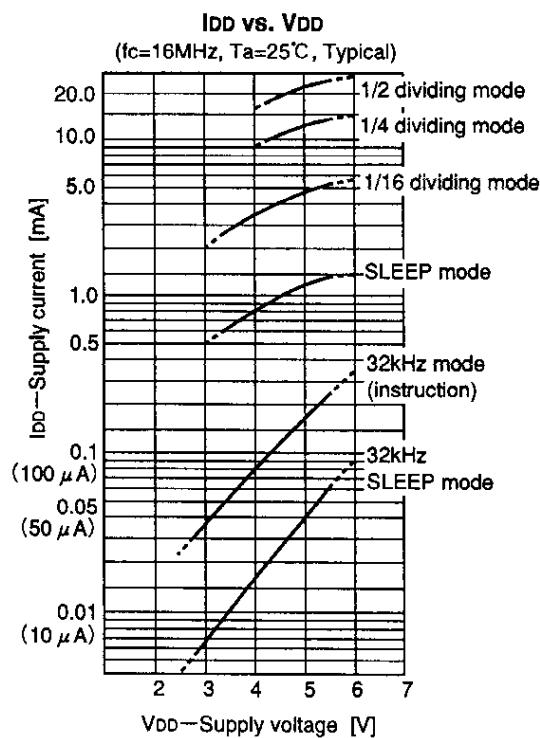
Manufacturer	Model	fc (MHz)	C1 (pF)	C2 (pF)	Rd (Ω)	Circuit example		
RIVER ELETEC CO., LTD.	HC-49/U03	8.00	10	10	0	(i)		
		10.00						
		12.00	5	5				
		16.00						
KINSEKI LTD.	HC-49/U (-S)	8.00	16	12	0	(i)		
		10.00	16	12				
		12.00	12	12				
		16.00	12	12				
	P3	32.768kHz	30	18	470k	(ii)		

Those marked with an asterisk (*) signify types with built-in ground capacitance (C₁, C₂).

Mask option table

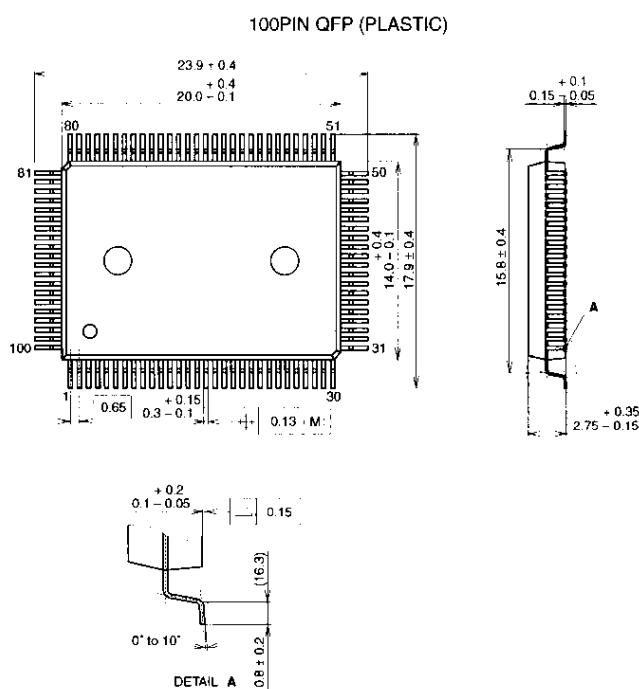
Item	Content	
Reset pin pull-up resistor	Non-existent	Exist
Input circuit format*	CMOS schmitt	TTL schmitt

* The input circuit format can be selected each for PG4 pin and PG5 pin.

Characteristics Curve

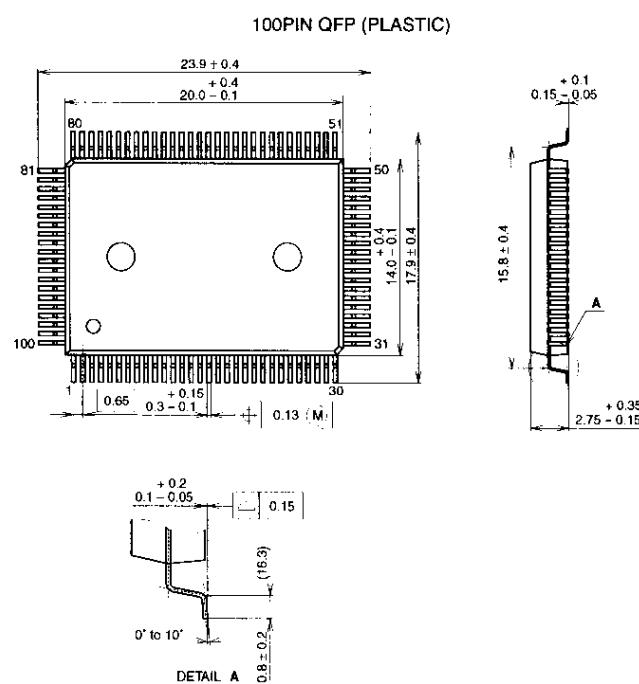
Package Outline

Unit: mm



SONY CODE	QFP-100P-L01
EIAJ CODE	QFP100-P-1420
JEDEC CODE	-----

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.7g



SONY CODE	QFP-100P-L01
EIAJ CODE	QFP100-P-1420
JEDEC CODE	-----

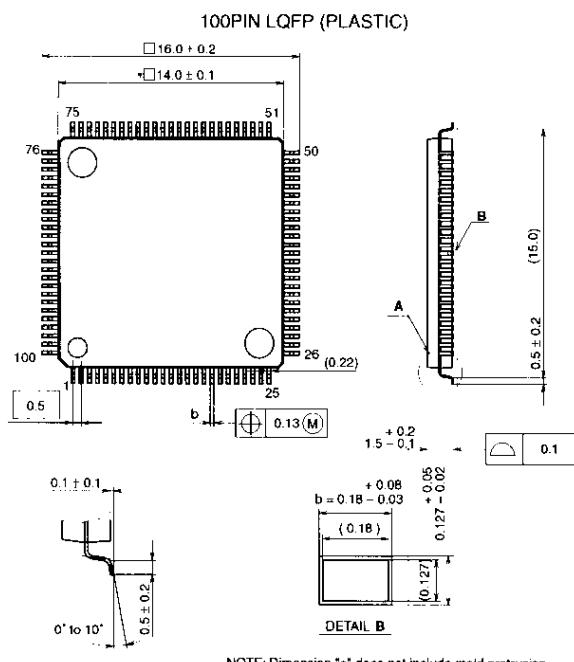
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.7g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	42 ALLOY
SOLDER COMPOSITION	Sn-Bi-Bi: 1-4wt%
PLATING THICKNESS	5-18µm

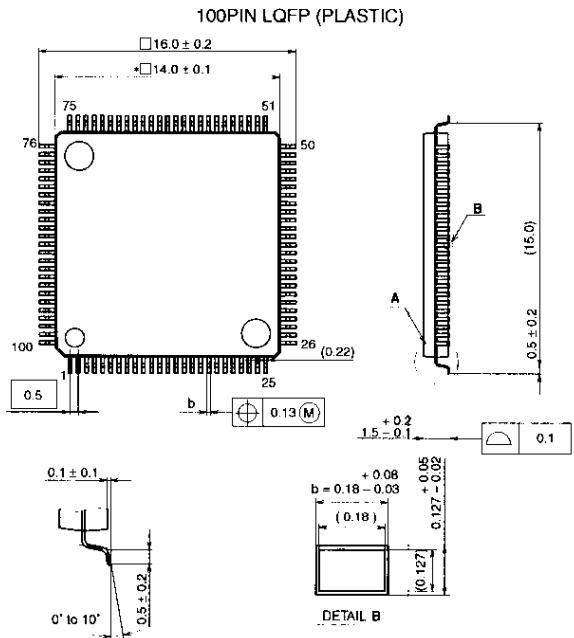
Package Outline

Unit: mm



SONY CODE	LQFP-100P-L01
EIAJ CODE	P-LQFP100-14x14-0.5
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 / COPPER ALLOY
PACKAGE MASS	0.7g



SONY CODE	LQFP-100P-L01
EIAJ CODE	P-LQFP100-14x14-0.5
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 / COPPER ALLOY
PACKAGE MASS	0.7g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	42 ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18µm